

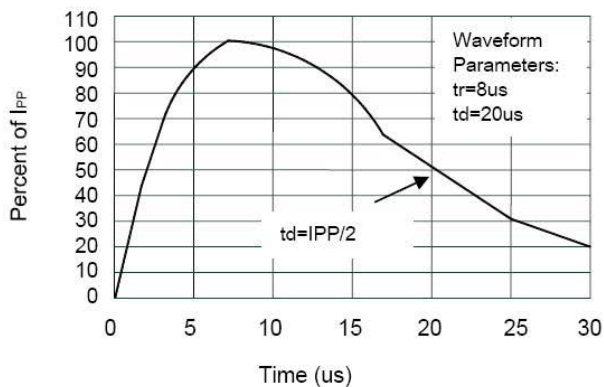


### Absolute Maximum Rating

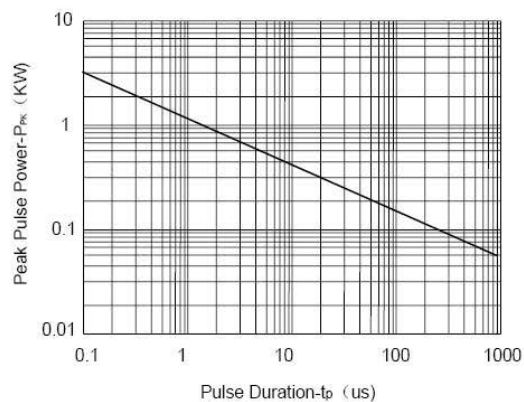
Symbol	Parameter	Value	Units
V <sub>ESD</sub>	ESD per IEC 61000-4-2 (Air)	±30	kV
	ESD per IEC 61000-4-2 (Contact)	±30	
P <sub>PP</sub>	Peak Pulse Power (8/20μs)	350	W
T <sub>OPT</sub>	Operating Temperature	-55/+150	°C
T <sub>STG</sub>	Storage Temperature	-55/+150	°C
T <sub>L</sub>	Lead Soldering Temperature	260 (10 sec.)	°C

### Electrical Characteristics (T = 25°C)

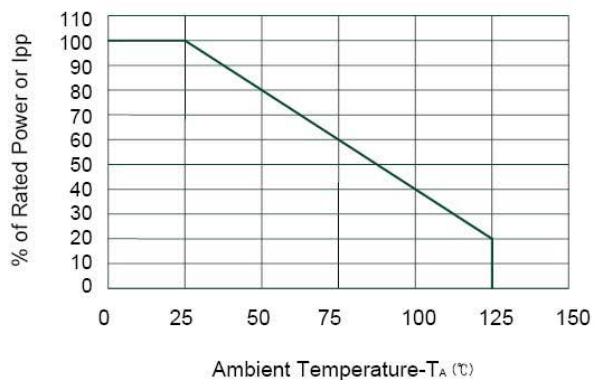
PART NUMBER	V <sub>RWM</sub>	V <sub>B</sub>	I <sub>T</sub>	V <sub>C@1A</sub>	V <sub>C</sub>		I <sub>R</sub>	C <sub>T</sub>	DEVICE MARKING
	(V) (max.)	(V) (min.)	(mA)	(V) (max.)	(V) (max.)	(@A)	(μA) (max.)	(pF) (max.)	
TS0311LEX	3.3	4.5	1	6	13	15	0.1	500	03W
TS0511LEX	5	6.0	1	10	24	19	0.1	160	05W
TS0811LEX	8	9.2	1	15	28	15	0.1	140	08W
TS1211LEX	12	13.3	1	19	32	13	0.1	120	12W
TS1511LEX	15	16.7	1	24	36	10	0.1	100	15W
TS1811LEX	18	20.4	1	28	45	8	0.1	80	18W
TS2411LEX	24	26.7	1	36	50	7	0.1	60	24W
TS3611LEX	36	40.0	1	50	60	6	0.1	40	36W
TS4811LEX	48	52.0	1	65	70	5	0.1	40	48W



**Pulse Waveform**



**Non-Repetitive Peak Pulse Power vs. Pulse Time**



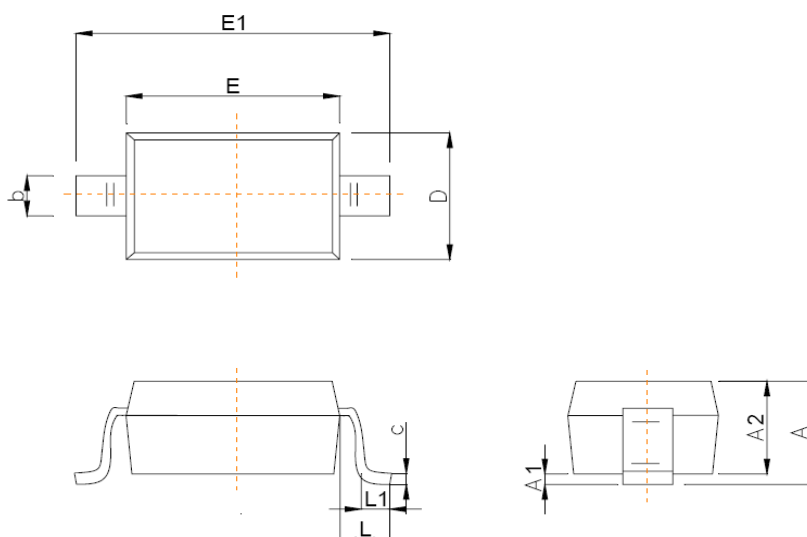
**Power Derating Curve**

## Package Outline

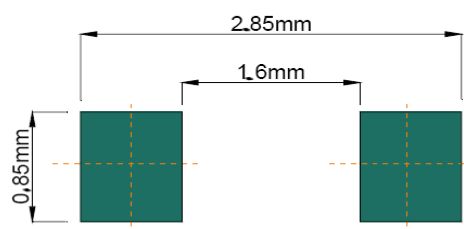
- SOD323 package



## Package Outline Dimensions



Symbol	Dimensions In Millimeters	
	Min	Max
A		1.00
A1	0.000	0.100
A2	0.800	0.900
b	0.250	0.350
c	0.080	0.150
D	1.200	1.400
E	1.600	1.800
E1	2.500	2.700
e	1.800	2.040
L	0.475 REF	
L1	0.250	0.400
θ	0°	8°



**Recommended Pad outline**